

IN THE CLAIMS:

Please add new independent Claim 12 as shown below. The claims, as pending in the subject application, now read as follows:

1. (Previously presented) A printed wiring board comprising:

a substrate having two opposite surfaces and a plurality of soldering through holes formed in said substrate, each of said plurality of soldering through holes opening in said opposite surfaces for inserting leads of an inserted component to be mounted onto the printed wiring board and for soldering said leads of an inserted component onto said substrate,

wherein each of said plurality of soldering through holes has an inner peripheral surface and a pair of lands, each land of said pair of lands being formed on respective ones of said opposite surfaces and formed continuously over said inner peripheral surface,

wherein at least one land of said pair of lands is connected to at least one wiring pattern at a connection portion;

wherein said connection portion is maintained in a state not wetted by solder; and

wherein, except for said connection portion, said at least one land of said pair of lands is maintained in a state wetted by solder.

2. (Canceled)

3. (Previously presented) A printed wiring board as claimed in claim 1, wherein said connection portion is maintained in a state not wetted by solder using a material not wetted by solder coated onto said pair of lands.

4. (Previously presented) A printed wiring board as claimed in claim 3, wherein the material not wetted by solder is a solder resist.

5. (Previously presented) A printed wiring board as claimed in claim 3, wherein the material not wetted by solder is a silk-screen pattern.

6. (Previously presented) A printing wiring board as claimed in claim 3, wherein the material not wetted by solder comprises a solder resist and a silk-screen pattern laminated onto each other.

7. (Previously presented) A printed wiring board as claimed in claim 1, wherein said connection portion is maintained in a state not wetted by solder using deactivation treatment means for oxidizing at least a part of the surface of at least one land of said pair of lands.

8. (Previously presented) A printed wiring board as claimed in claim 1, wherein lead solder is applied to the leads of the inserted component prior to insertion of said leads into said through-holes of said printed wiring board.

9. (Original) A printed wiring board as claimed in claim 1, wherein the inserted component is soldered onto said substrate by flow soldering using lead-free solder.

10. (Previously Presented) A printed wiring board as claimed in claim 9, wherein the lead-free solder contains Bismuth.

11. (Canceled)

12. (New) A printed wiring board comprising:

a substrate having two opposite surfaces and a plurality of soldering through holes formed in said substrate, each of said plurality of soldering through holes opening in said opposite surfaces for inserting leads of an inserted component to be mounted onto the printed wiring board and for soldering said leads of an inserted component onto said substrate,

wherein each of said plurality of soldering through holes has a conductive inner peripheral surface and a pair of conductive lands, each land of said pair of conductive lands being formed on respective ones of said opposite surfaces,

wherein at least one land of said pair of conductive lands is connected to at least one wiring pattern at a connection portion,

wherein said connection portion is maintained in a state not wetted by solder, and

wherein said at least one land of said pair of conductive lands is maintained in a state wetted by solder.